



## **Features**

- 6-Pin SMD package
- Fast warm-up
- Frequency Range, 10 MHz to 40 MHz
- Standard freq: 10, 12.8, 20, 24.576, 25, 30.72 MHz
- High Relability (based on fully intergrated Design)
- Low Power

## **Applications**

- Base stations 5G & 4 G)
- Test equipment
- Small Cell
- Military communication equipment
- Stratum 3
- SyncE; 1588

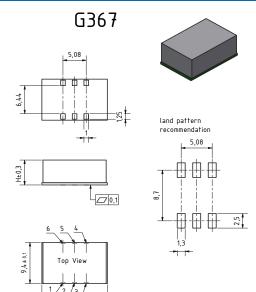
## **Performance Specifications**

Frequency Stabilities <sup>1</sup> 10 to 40 MHz						
Parameter	Min	Typical	Max	Units	Condition	
vs. operating temperature range (referenced to +25°C)	-20 -10 -20		+20 +10 +20	ppb ppb ppb	-40 to +85°C -40 to +85°C -40 to +95°C	Options <sup>5</sup>
slope	-2		+2	ppb/°C	@ Temp stab. +-10ppb	
Initial tolerance vs. supply voltage change vs. load change vs. aging / day vs. aging / year vs. aging / 10 years	-0.5 -10 -10 -5 500 -3	±2	+0.5 +10 +10 +5 +500	ppm ppb ppb ppb ppm	at time of shipment, nominal EFC $V_s\pm5\%$ static Load $\pm5\%$ static after 30 days of operation after 30 days of operation after 30 days of operation	
Holdover drift			5	ppb	over 24 hours, constant temperature (<± after 30 days continous opperation	1°C) ;
Start up time			200	msec		
Warm-up time			3	minutes	to ±20ppb of final frequency (1 hour read @ +25°C	ding)
Loop bandwith for wander generation compliance	3			mHz	MTIE compliant with GR-1244 Fig 5-5 TDEV compliant with GR- 1244 Fig 5-4 measurement setup: oscillator stabilized hours at Constant Temperature (±1°C, s air), data collected over 100,000 seconds second intervals (-3dB cutoff, 1st order h pass loop filter)	l; d 24 still at 1

# **Performance Specifications**

Supply Voltage (Vs)						
Parameter	Min	Typical	Max	Units	Condition	
Supply voltage (standard)	3.135	3.3	3.465	VDC		
Dower concumption		1.3	1.5	Watts	during warm-up	
Power consumption		0.65	0.8	Watts	steady state @ +25℃	
			RF Outpu	t		
Signal [standard]		LVHC	CMOS			
Load		15		pF		
Signal Level (Vol)			0.4	VDC	with Vs=3.3V and 15pF Lo	ad
Signal Level (Voh)	2.97	3.3		VDC	with Vs=3.3V and 15pF Lo	ad
Duty Cycle	45		55	%	@ (Voh-Vol)/2	
Ron		26.5		Ω		
Roff		22		Ω		
		Frequ	uency Tunir	ig (EFC)		
Tuning Range		Fixed OCX	O; No adjust			Opti- on <sup>5</sup>
Tuning Range	±3		±8	ppm	not available for all frequencies	ō°
Linearity	10%					
Tuning Slope		Pos	itive			
Control Voltage Range	0.0	1.4	2.8	VDC		
		Add	itional Para	meters		
Phase Noise <sup>3</sup>		-99 -125 -145 -155 -160	-90 -120 -140 -150 -155	dBc/Hz dBc/Hz dBc/Hz dBc/Hz dBc/Hz	10 Hz 100 Hz 1 kHz 10 kHz 100kHz	@ 20MHz
Weight			1.0	g		
Processing & Packing	H	landling & Pr	ocessing No	te		
Absolute Maximum Ratings						
Supply voltage (Vs)	3.8 V with Vs=3.3 VDC		with Vs=3.3 VDC			
Output Load			50	pF		
Operable Temperature Range	-40		+95	°C		
Storage Temperature Range	-40		+125	°C		

# **Outline Drawing / Enclosure**

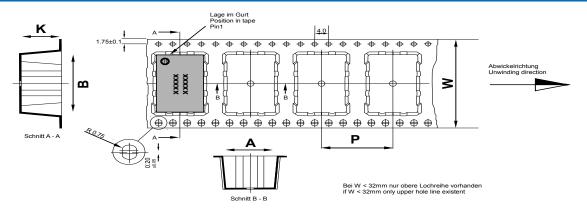


14,3±0,1

	OX-502
Height "H"	cover material
6.2	plastic

Pin Connections			
1	I.C (Do not connect) / EFC (option)		
2	N.C		
3	Ground (Case)		
4	RF Output		
5	N.C		
6	Supply Voltage Input		

# **Standard Shipping Method (OX-502)**



Maßangaben in mm:

Dimension in mm:

A, B und K Maße von Bauelement abhängig

A, B und K are dependent uppon component dimensions production tolerance complying DIN IEC 286-3

Fertigungstoleranzen entsprechen der DIN IEC 286-3 product

All dimensions in millimeters unless otherwise stated

Enclosure Type	Tape Width W (mm)	Quantity per meter	Quantity per reel	Dimension P
OX-502 (6.2 mm)	24	83.3	400	12

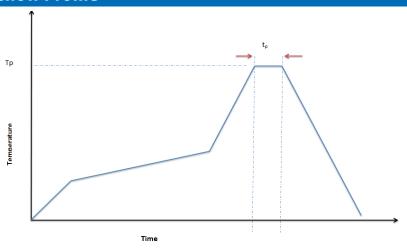
## **Reflow Profile**

TP: max  $250^{\circ}$ C (@ solder joint, customer board level) Tp: max: 10...40 sec

Additional Information:

This SMD oscillator has been designed for pick and place reflow soldering

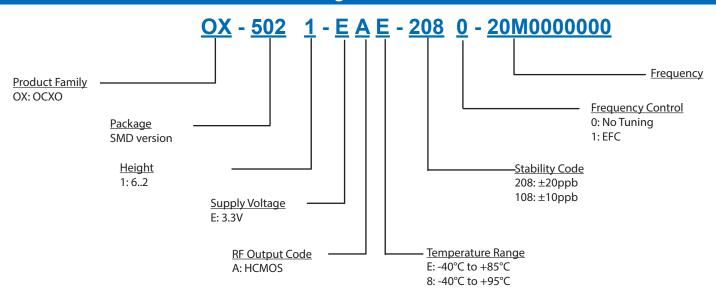
SMD oscillators must be on the top side of the PCB during the reflow process.



# **Additional Environmental Conditions**

Parameter	Description
Temperature Cycling	JESD22-A104-D Cond.G - 500cycles -40/+125C;cycle time 30min
Vibration, Sine	MIL-STD-883 Meth 2007 Cond A - 20g 20-2000Hz 4x in each 3 axis 4min sweep time
Mechanical Shock	MIL-STD-202 Meth 213B Cond. F - 1500g 0,5ms 6 shocks in each direction
Solderability	J-STD-002C Cond. A, Trough hole device; Cond.B, SMD ( correspond to MIL-STD-883 Meth 2003) - 255C (diving Time 5 0,5sec.) Dip&Look with 8h damp pre-treatment: solder wetting >95%
Solvent resistance	MIL-STD-883 Meth 2003) - 255C (diving Time 5 0,5sec.) Dip&Look with
ESD	8h damp pre-treatment: solder wetting >95%
Moisture Sensit.	JESD22-A113-B - only if > MSL 1
RoHS compliance	100% RoHS 6 compliant
Washable	non-washable device
High temp operating life(HTOL)	MIL-STD-202 Meth108A Cond C - 1000h @ 105C power on
Low temp operating life(LTOL)	IEC 60068-2-1 Cond. Ae - 1000h @ -40C power on

## **Ordering Information**



#### **Notes:**

- 1. Contact factory for improved stabilities or additional product options. Not all options and codes are available at all frequencies.
- 2. Unless other stated all values are valid after warm-up time and refer to typical conditions for supply voltage, frequency control voltage, load, temperature (25°C).
- 3. Phase noise degrades with increasing output frequency.
- 4. Subject to technical modification.
- 5. Contact factory for availability.

### **Contact Information**

#### USA:

100 Watts Street Mt Holly Springs, PA 17065 Tel: 1.717.486.3411

Fax: 1.717.486.5920

#### **Europe:**

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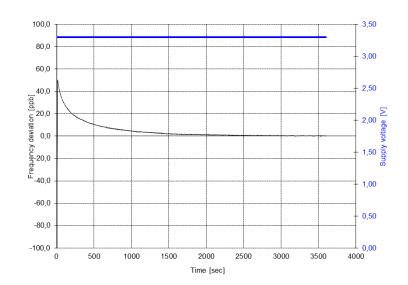
# typical perforamce data

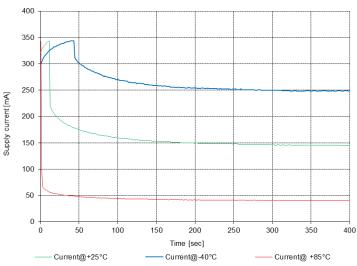
darin i an	TATO MISS. T.I.	to /Euco	110000	vs. time
LVDICA	ı warın u	10 11 14 14 0	wency	vs. ume

## typical current consumption during power on

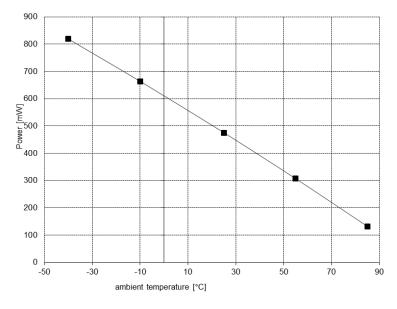
@ OX-5021-EAE-1080-20M000

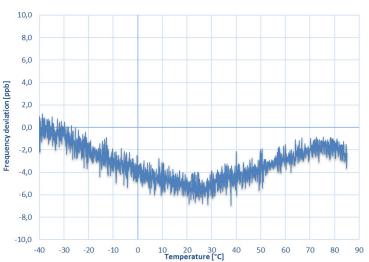
@ OX-5021-EAE-1080-20M000



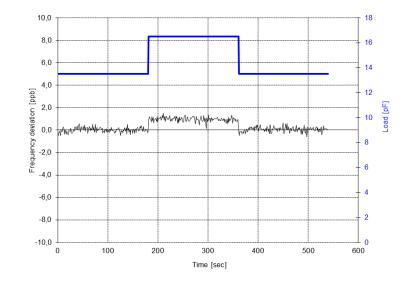


typical power consumption vs. operating temperauture	typical frequency vs. temperature stability
@ OX-5021-EAE-1080-20M000	@ OX-5021-EAE-1080-20M000

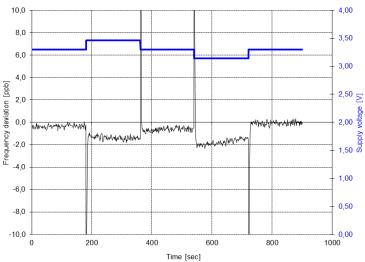




# typical perforamce data typical frequency vs. load change typical frequeny vs. supply voltage

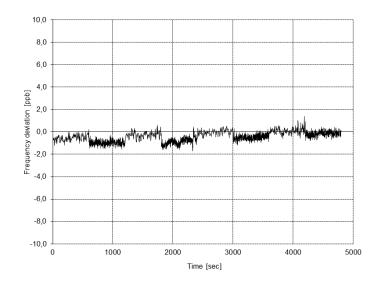


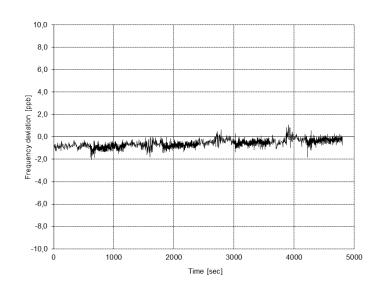
@ OX-5021-EAE-1080-20M000



@ OX-5021-EAE-1080-20M000

typical frequency. vs cycled airflow without additional cover	typical frequency. vs cycled airflow with additional cover	
@ OX-5021-EAE-1080-20M000	@ OX-5021-EAE-1080-20M000	





typical perforance data			
typical MTIE @ 3mHz loop Bandwidth	typical TDEV @ 3mHz loop Bandwidth		
@ OX-5021-FAF-1080-20M000	@ OX-5021-FAF-1080-20M000		

